

Figure 2(a)

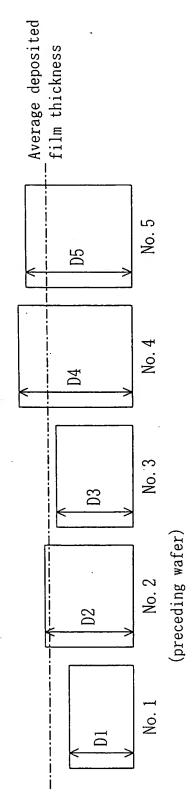
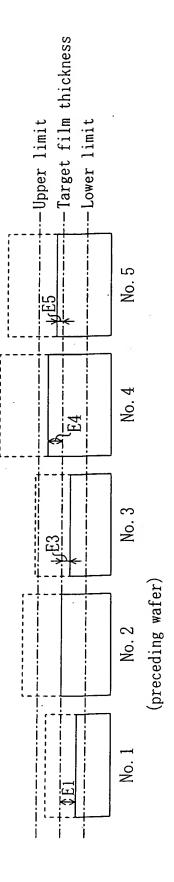


Figure 2(b)



-S21 Perform the first to i-th (1  $\leq$  i  $\leq$  n-1) processes (including film deposition process) for semiconductor wafers. -S22 Perform the j-th (i  $\leq$  j  $\leq$  n-1) process of measuring the processing results of the film deposition process on the semiconductor wafers (processing result measuring process) S23 Perform the (j+1)th to (n-1)th processes (including etching process) for the semiconductor wafers. -S24 Determine as a measuring wafer a semiconductor wafer having processing results closest to the average of the processing results of the film deposition process. -S25 Perform the n-th process (post-etching film thickness measuring process) for the measuring wafer determined at step S24.

Figure 4(a)

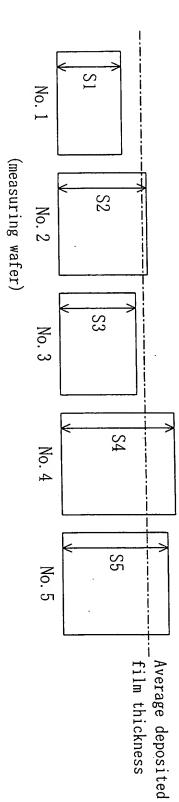
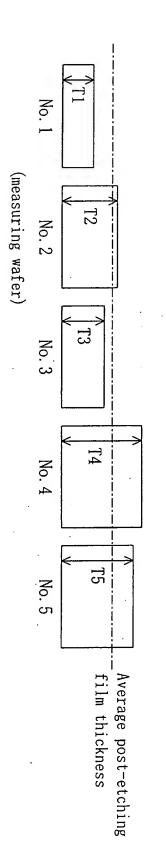
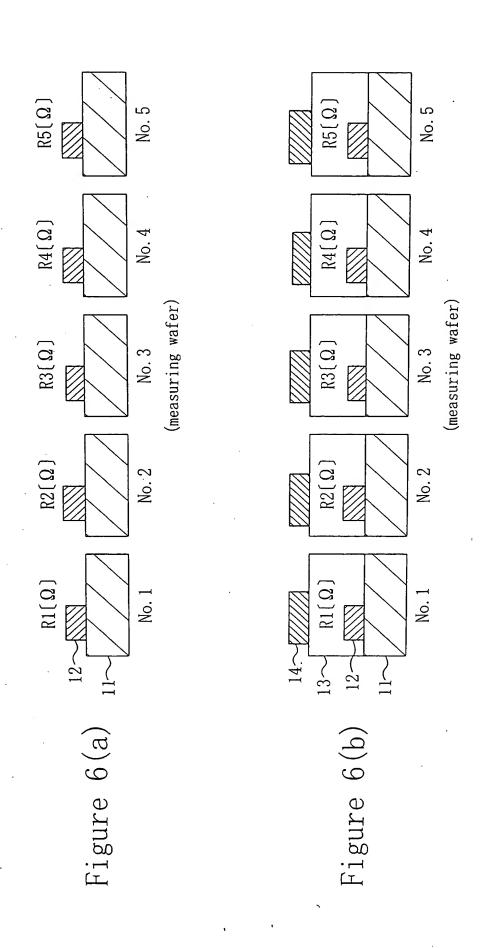


Figure 4(b)



S31 Perform the first to i-th (1  $\leq$  i  $\leq$  n-1) processes (including lower line formation process) for semiconductor wafers. -S32 Perform the j-th (i  $\leq$  j  $\leq$  n-1) process of measuring the processing results of the lower line formation process on the semiconductor wafers (processing result measuring process) -S33 Perform the (j+1)th to (n-1)th processes (including upper line formation process) for the semiconductor wafers. S34 Determine as a measuring wafer a semiconductor wafer having processing results most largely deviated from the target value of the processing results of the lower line formation process. -S35 Perform the n-th process (step measuring process) for the measuring wafer determined at step S34.



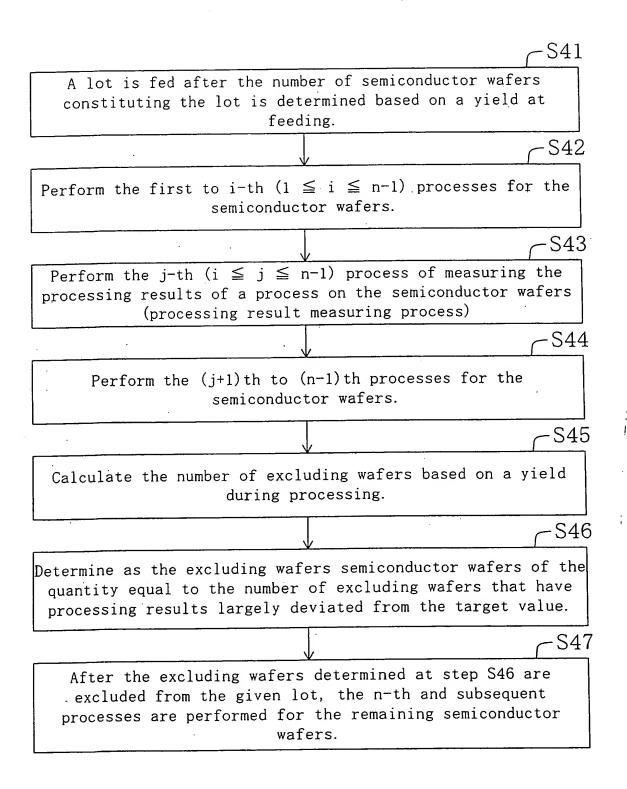


Figure 8

